

• Product Summary

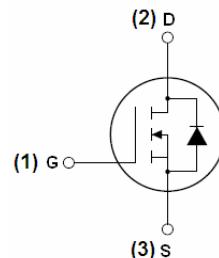
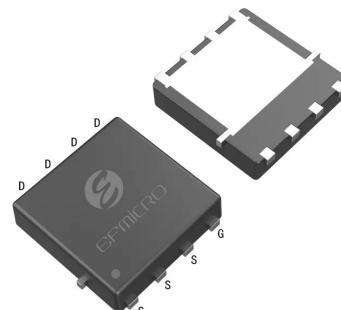
| Part # | V _{DS} | R _{DS(on).typ} (@V _{GS} =10V) | R _{DS(on).typ} (@V _{GS} =4.5V) | I _D |
|------------|-----------------|--|---|----------------|
| EFM060N03M | 30V | 6mΩ | 9mΩ | 60A |

• Description

- The EFM060N03M is the high cell density trenched
- N-ch MOSFETs which provide excellent
- RDSON and gate charge for most of the
- synchronous buck converter applications.
- The EFM060N03M meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.

• Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology


N-Channel MOSFET

DFN3x3-8L

• Ordering Information:

| | |
|---------------------------|---------------|
| Part NO. | EFM060N03M |
| Marking | 060N03M ***** |
| Packing Information | REEL TAPE |
| Basic ordering unit (pcs) | 5000 |

• Absolute Maximum Ratings (T_C=25°C)

| Parameter | Symbol | Limit | Unit |
|--|-----------------------------------|------------|------|
| Drain-Source Voltage | V _{DS} | 30 | V |
| Gate-Source Voltage | V _{GS} | ±20 | V |
| Drain Current-Continuous | I _D | 60 | A |
| Drain Current-Pulsed ^(Note 1) | I _{DM} | 120 | A |
| Maximum Power Dissipation | P _D | 58 | W |
| Operating Junction and Storage Temperature Range | T _J , T _{STG} | -55 To 150 | °C |

• Thermal Characteristic

| | | | |
|---|------------------|-----|------|
| Thermal Resistance, Junction-to-Ambient ^(Note 2) | R _{θJC} | 2.5 | °C/W |
|---|------------------|-----|------|

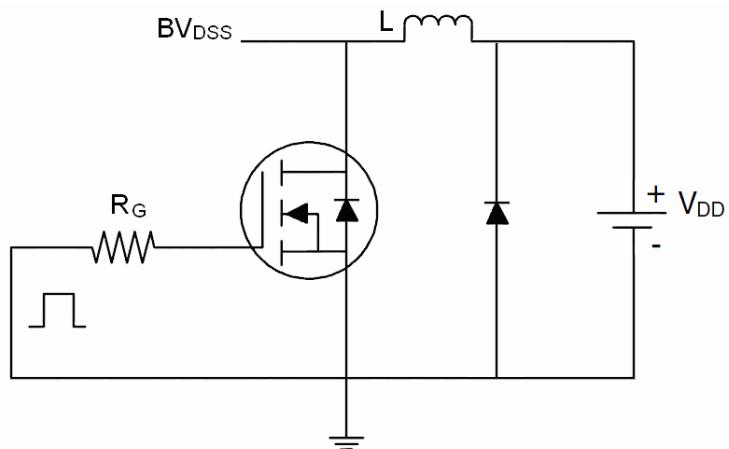
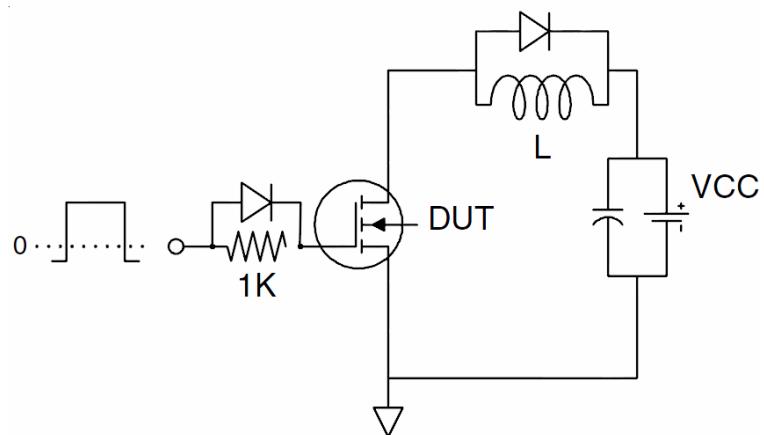
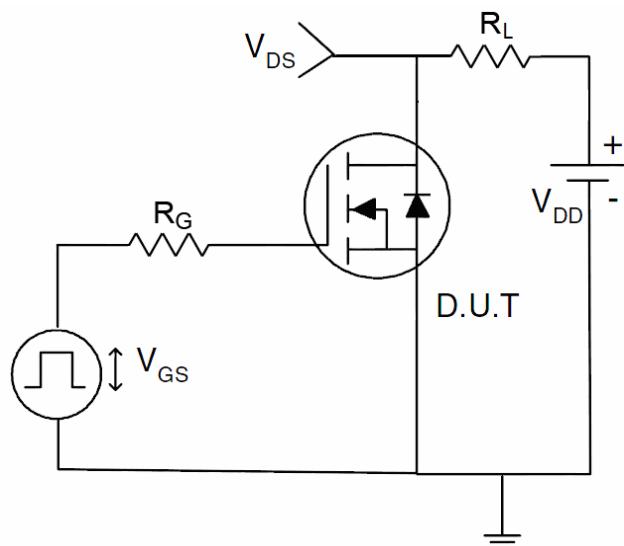
• Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

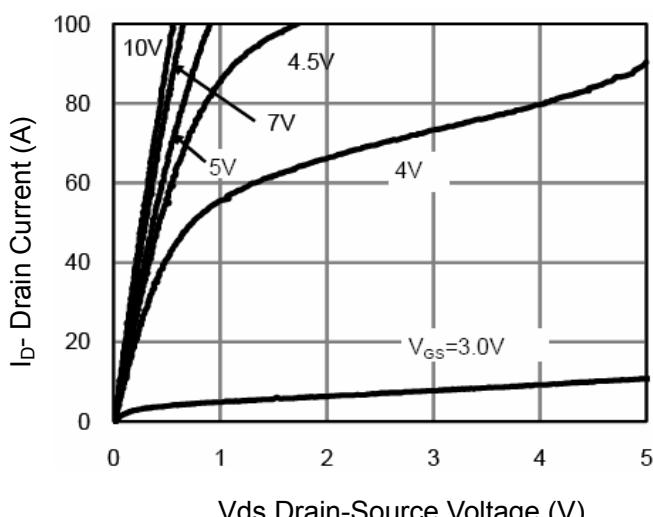
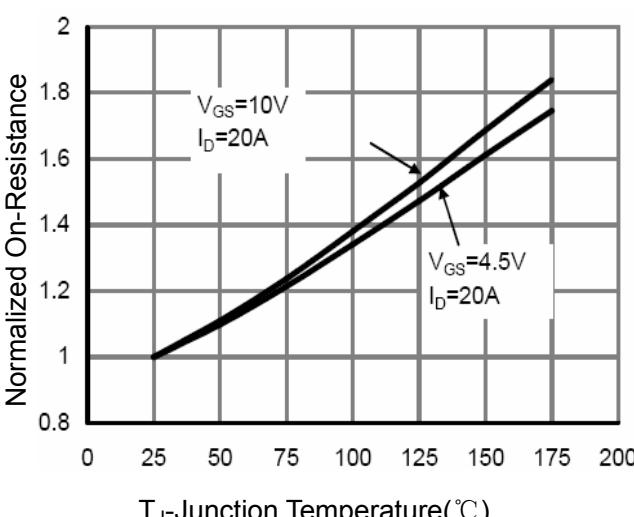
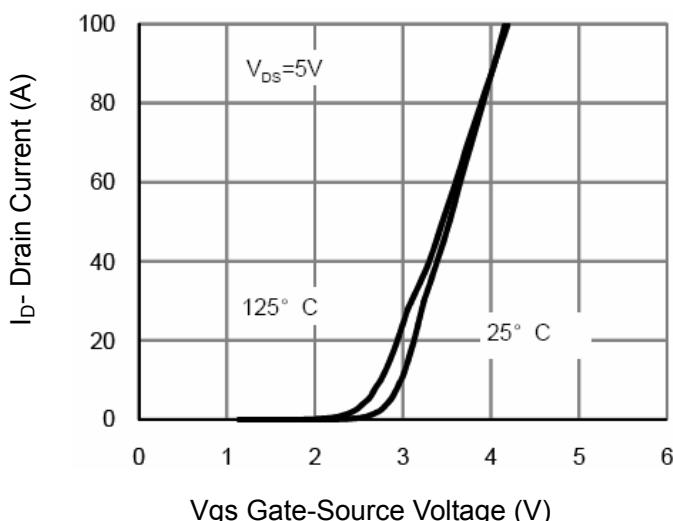
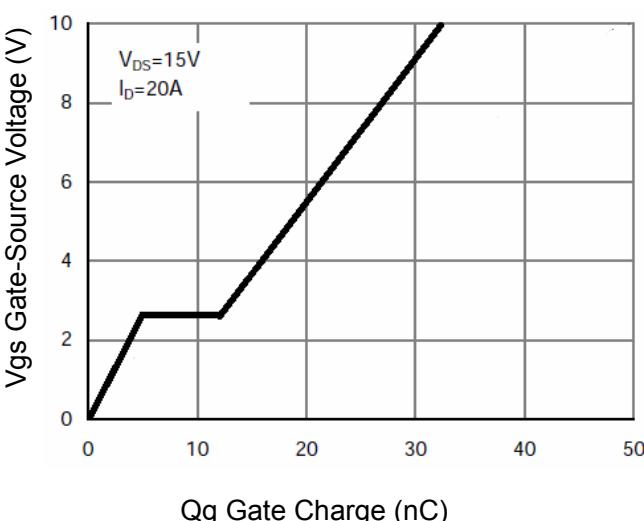
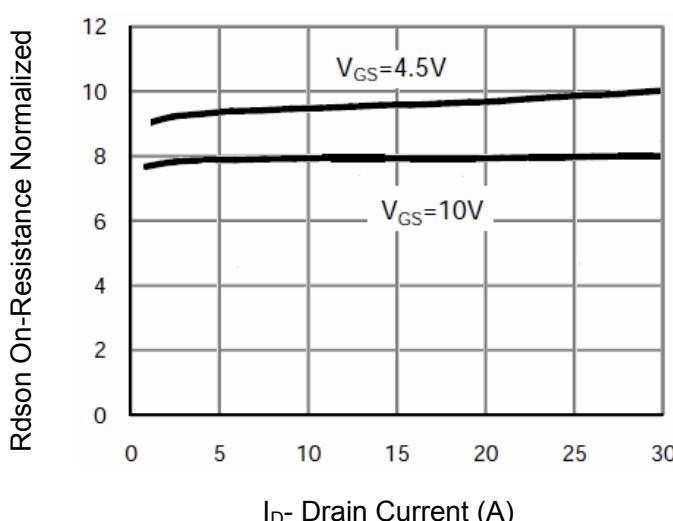
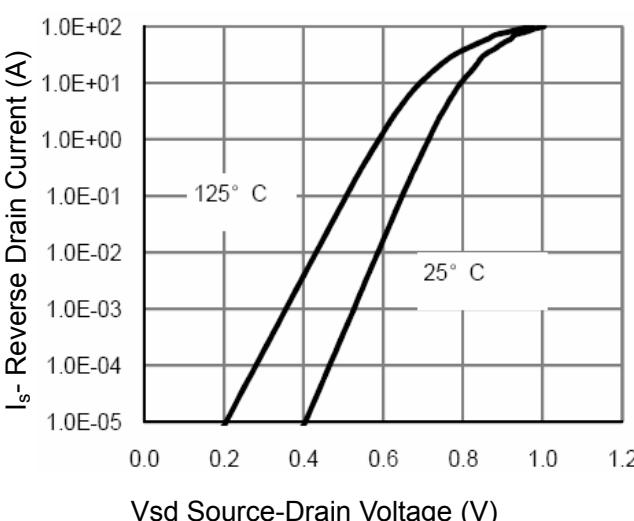
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|--------------------------|---|-----|------|-----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V} I_{\text{D}}=250\mu\text{A}$ | 30 | -- | -- | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=30\text{V} V_{\text{GS}}=0\text{V}$ | -- | -- | 1 | nA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V} V_{\text{DS}}=0\text{V}$ | -- | -- | ± 100 | nA |
| On Characteristics <small>(Note 3)</small> | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS(th)}}$ | $V_{\text{DS}}=V_{\text{GS}} I_{\text{D}}=250\mu\text{A}$ | 1.0 | 1.6 | 2.5 | V |
| Drain-Source On-State Resistance | $R_{\text{DS(ON)}}$ | $V_{\text{GS}}=10\text{V} I_{\text{D}}=20\text{A}$ | -- | 6 | 7.5 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V} I_{\text{D}}=20\text{A}$ | -- | 9 | 11 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=5\text{V} I_{\text{D}}=20\text{A}$ | -- | 20 | -- | S |
| Dynamic Characteristics <small>(Note 4)</small> | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=15\text{V} V_{\text{GS}}=0\text{V}$ $F=1.0\text{MHz}$ | -- | 1150 | -- | PF |
| Output Capacitance | C_{oss} | | -- | 380 | -- | PF |
| Reverse Transfer Capacitance | C_{rss} | | -- | 260 | -- | PF |
| Switching Characteristics <small>(Note 4)</small> | | | | | | |
| Turn-on Delay Time | $t_{\text{d(on)}}$ | $V_{\text{DD}}=15\text{V} I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=10\text{V} R_{\text{G}}=1.8\Omega$ | -- | 10 | -- | nS |
| Turn-on Rise Time | t_{r} | | -- | 8 | -- | nS |
| Turn-Off Delay Time | $t_{\text{d(off)}}$ | | -- | 25 | -- | nS |
| Turn-Off Fall Time | t_{f} | | -- | 5 | -- | nS |
| Total Gate Charge | Q_{g} | $V_{\text{DS}}=15\text{V} I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=10\text{V}$ | -- | 32 | -- | nC |
| Gate-Source Charge | Q_{gs} | | -- | 4.9 | -- | nC |
| Gate-Drain Charge | Q_{gd} | | -- | 6.9 | -- | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage <small>(Note 3)</small> | V_{SD} | $V_{\text{GS}}=0\text{V} I_{\text{S}}=20\text{A}$ | -- | 0.85 | 1.2 | V |
| Diode Forward Current <small>(Note 2)</small> | I_{S} | | -- | -- | 50 | A |

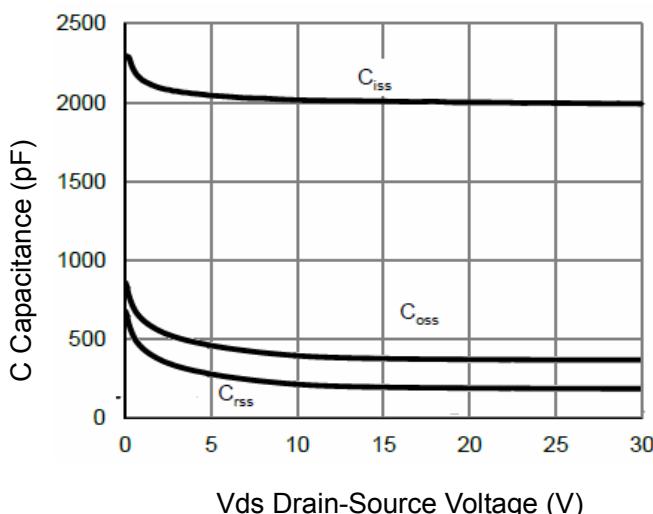
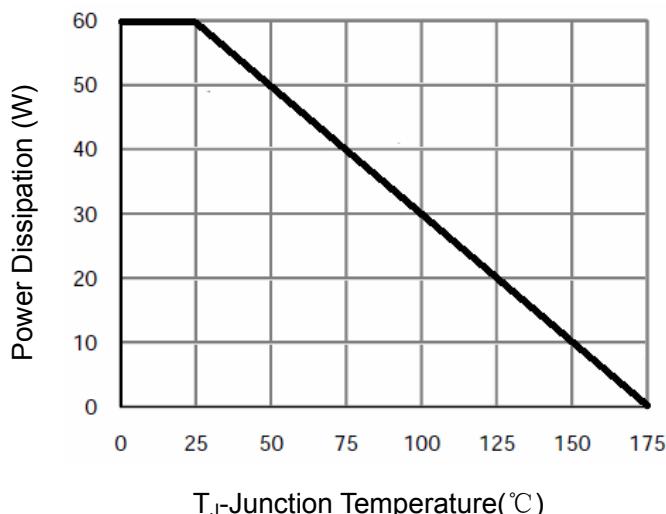
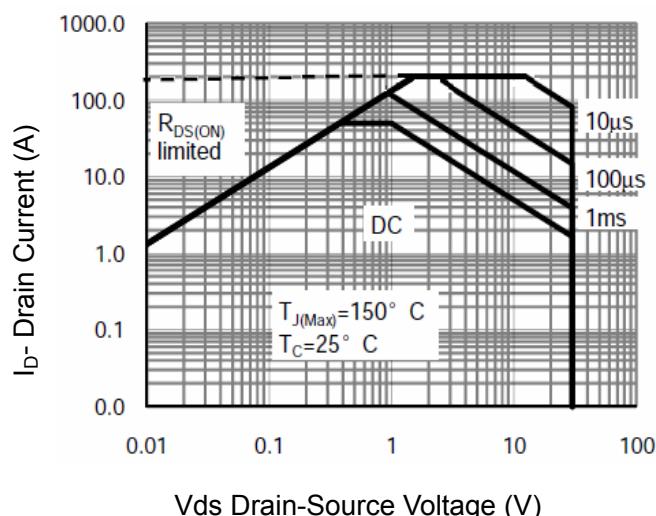
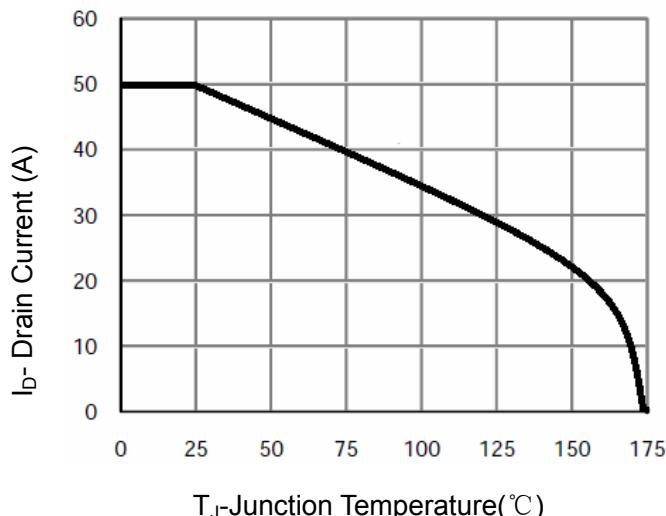
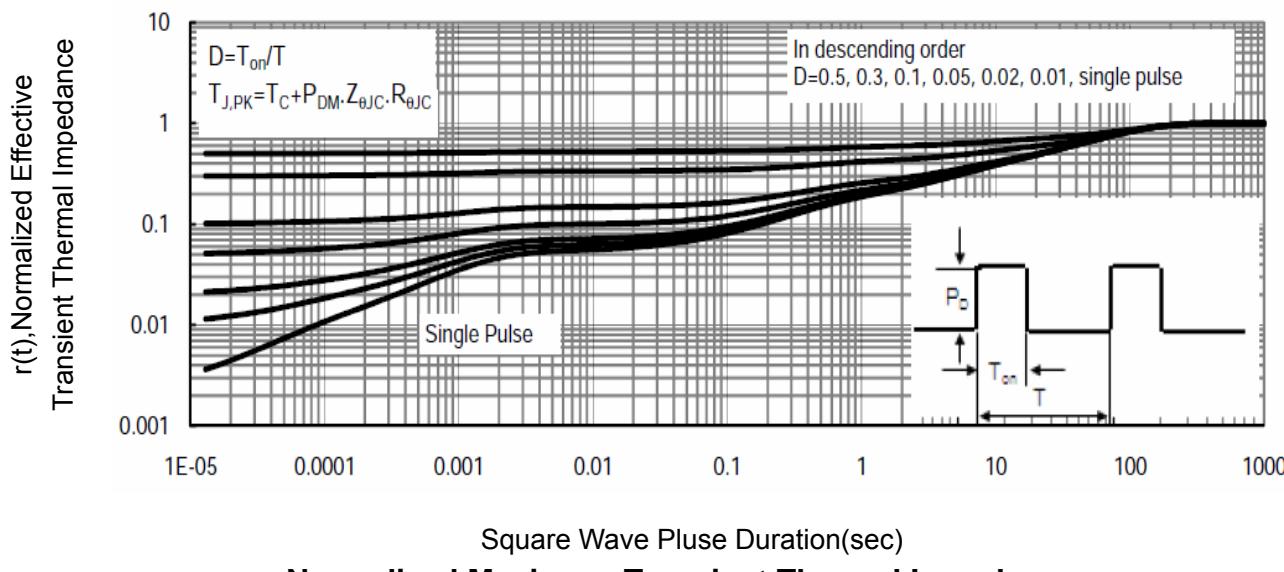
Notes:

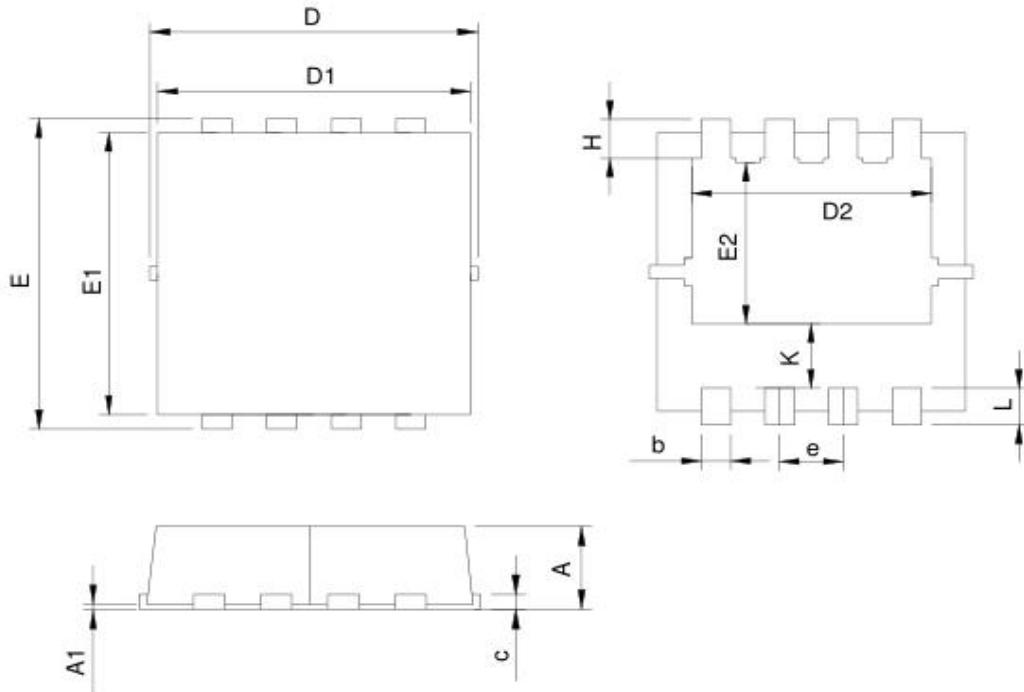
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_j=25^\circ\text{C}$, $V_{\text{DD}}=15\text{V}$, $V_{\text{G}}=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$

- Typical Characteristics

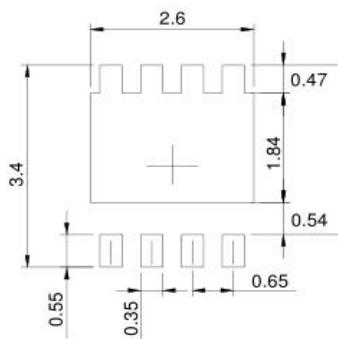
1) E_{AS} test Circuits

2) Gate charge test Circuit:

3) Switch Time Test Circuit:



Figure 1 Output Characteristics

Figure 4 Rdson-JunctionTemperature

Figure 2 Transfer Characteristics

Figure 5 Gate Charge

Figure 3 Rdson- Drain Current

Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 ID Current- Junction Temperature

Normalized Maximum Transient Thermal Impedance

•DFN3*3 Package Outline


| SYMBOL | DFN3.3x3.3-8 | | | |
|--------|--------------|------|-----------|-------|
| | MILLIMETERS | | INCHES | |
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.70 | 1.00 | 0.028 | 0.039 |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 |
| b | 0.25 | 0.35 | 0.010 | 0.014 |
| c | 0.14 | 0.20 | 0.006 | 0.008 |
| D | 3.10 | 3.50 | 0.122 | 0.138 |
| D1 | 3.05 | 3.25 | 0.120 | 0.128 |
| D2 | 2.35 | 2.55 | 0.093 | 0.100 |
| E | 3.10 | 3.50 | 0.122 | 0.138 |
| E1 | 2.90 | 3.10 | 0.114 | 0.122 |
| E2 | 1.64 | 1.84 | 0.065 | 0.072 |
| e | 0.65 BSC | | 0.026 BSC | |
| H | 0.32 | 0.52 | 0.013 | 0.020 |
| K | 0.59 | 0.79 | 0.023 | 0.031 |
| L | 0.25 | 0.55 | 0.010 | 0.022 |

RECOMMENDED LAND PATTERN


UNIT: mm